



ATTACHMENT C Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A cooling assembly for at least one board, the at least one board having mounted thereon a plurality of components including a first component and a further component, the cooling assembly comprising:

a first passage;

a first fan-suitable for passing air through the passage;

an isolation assembly for generally enclosing heat generated from the first component, ~~wherein the first component mounted on the at least one board is being~~ enclosed within the isolation assembly, the isolation assembly ~~in communication with~~ containing at least a part of the first passage, ~~wherein and~~ the isolation assembly is being removably attachable to a computer case without opening the computer case, ~~and wherein the passage is separate from another heat sensitive component within the computer case;~~

~~an alternate~~ a further passage configured to provide ~~an air flow path to~~ past the further component mounted on the at least one board outside of the isolation assembly;

and

a second fan-suitable for passing air through the ~~alternate~~ further passage.

2. (Canceled)

3. (Currently Amended) The cooling assembly of claim 1, wherein the ~~alternate~~ first passage includes a conduit, separate from the first and second fans, in communication with the isolation assembly.

4. (Original) The cooling assembly of claim 1, and further comprising a heat sink operably coupled to the first component.

5. (Original) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

6. (Original) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

7-31. (Canceled)

32. (Previously Presented) The cooling assembly of claim 4, wherein the heat sink comprises a passive heat sink.

33. (Previously Presented) The cooling assembly of claim 1, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

34. (Currently Amended) A cooling assembly for at least one board, the at least one board having mounted thereon a plurality of components including a first component and a further component, the cooling assembly comprising:

a first passage;

a first fan-suitable for passing air through the passage;

an isolation assembly for generally enclosing heat generated from the first component, ~~wherein the first component mounted on the at least one board is~~being enclosed within the isolation assembly, ~~and the isolation assembly in communication with~~containing at least a part of the first passage, ~~and wherein the passage is separate from another heat sensitive component within a computer case;~~

~~an alternate~~a further passage configured to provide ~~an air flow path to~~past the further component mounted on the at least one board outside of the isolation assembly;

and

a second fan-suitable for passing air through the ~~alternate~~further passage.

35. (Canceled)

36. (Previously Presented) The cooling assembly of claim 34, wherein the alternate passage includes a conduit in communication with the isolation assembly.

37. (Previously Presented) The cooling assembly of claim 34, and further comprising a heat sink operably coupled to the first component.

38. (Previously Presented) The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

39. (Canceled)

40. (Previously Presented) The cooling assembly of claim 37, wherein the heat sink comprises a passive heat sink.

41. (Previously Presented) The cooling assembly of claim 34, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

42. (Previously Presented) The cooling assembly of claim 1, wherein the first component comprises a processor.

43. (Previously Presented) The cooling assembly of claim 34, wherein the first component comprises a processor.

44. (Currently Amended) The cooling assembly of claim 1, further comprising:
an exhaust hole in communication with the first passage and suitable for venting air through the computer case.

45. (Currently Amended) The cooling assembly of claim 44, wherein an air path from the first fan through the exhaust hole passes through the first passage.

46. (Previously Presented) The cooling assembly of claim 44, wherein the cooling assembly is configured such that at least 80% of the air passing through the first fan is vented through the exhaust hole.

47. (Previously Presented) The cooling assembly of claim 44, wherein the cooling assembly is configured such that substantially all of the air passing through the first fan is vented through the exhaust hole.

48. (Currently Amended) The cooling assembly of claim 34, further comprising:
an exhaust hole in communication with the first passage and suitable for venting air through the computer case.

49. (Currently Amended) The cooling assembly of claim 48, wherein an air path from the first fan through the exhaust hole passes through the first passage.

50. (Previously Presented) The cooling assembly of claim 48, wherein the cooling assembly is configured such that at least 80% of the air passing through the first fan is vented through the exhaust hole.

51. (Previously Presented) The cooling assembly of claim 48, wherein the cooling assembly is configured such that substantially all of the air passing through the first fan is vented through the exhaust hole.